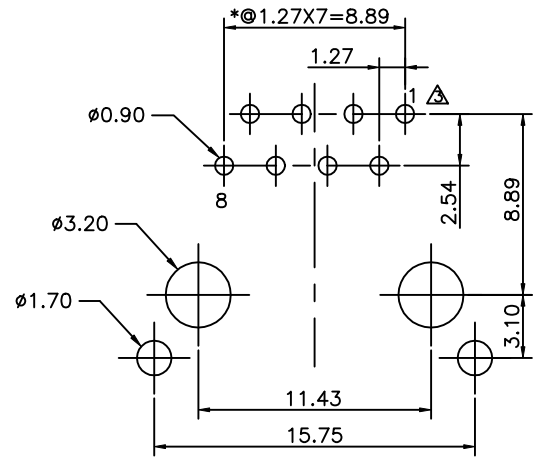
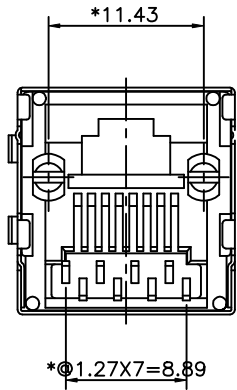
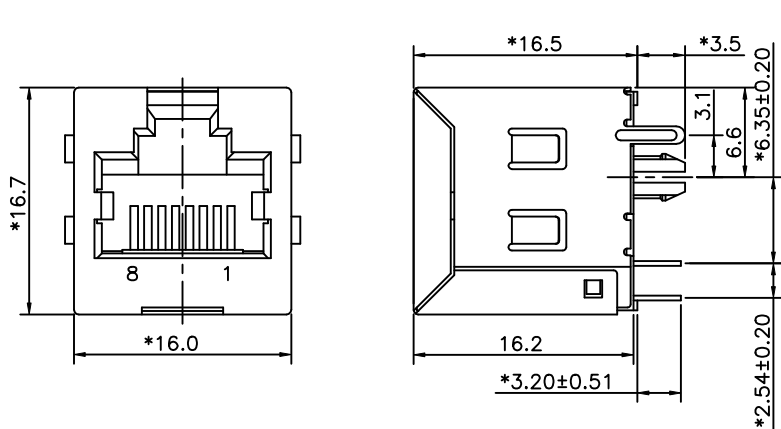
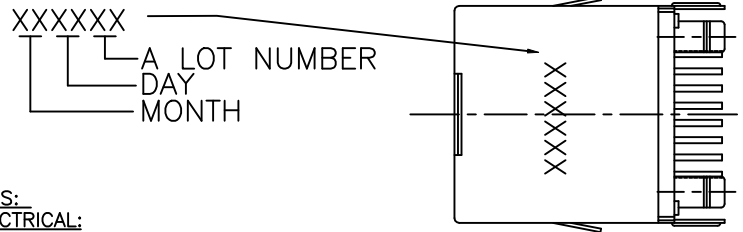


REVISION RECORD				
REV	ECO	DESCRIPTION	DRFT	CHKD
△		Modify Drawing	czh 07/23/03	
△		MODIFY DRAWING	AMONG 10/22/04	
△		ADD PART NO	CHULER 01/03/05	



PC Board Layout Component Side Shown



NOTES:

ELECTRICAL:

- VOLTAGE RATING : 125 VAC RMS.
- CURRENT RATING : 1.5 AMP.
- CONTACT RESISTANCE : 30 MILLIOHMS MAX.
- INSULATION RESISTANCE: 1000 MEGOHMS MIN @ 500 VDC.
- DIELECTRIC STRENGTH : 1000 VAC RMS 60Hz, 1MIN.

MECHANICAL:

- HOUSING MATERIAL : GLASS FILLED POLYESTER UL94V-0.
- CONTACT MATERIAL : PHOSPHOR BRONZE t=0.35mm.
- PLATING : GOLD PLATING OVER NICKEL.
- OPERATING LIFE : 750 CYCLES MIN.
- PCB RETENTION PRE-SOLDER : 1 LB MIN.
- PCB RETENTION POST-SOLDER: 10 LBS MIN.

ENVIRONMENTAL:

- STORAGE : -40°C TO +85°C.
- OPERATION: -40°C TO +85°C.

MATES WITH MODULAR PLUG CONFORMING TO

FCC PART 68, SUBPART F.

CUL FILE NO. E163191

PART NUMBER: E52D8-RX0X4X

- SHIELD PLATING:
 - 1- TIN PLATING
 - 2- NICKEL PLATING
- GOLD PLATING:
 - 1- 3u" 2- 6u"
 - 3- 15u" 4- 30u"
 - 5- 50u"
- 0-PBT+15%GF(BK)
- 1-PBT+30%GF (BK)

LEAD-FREE PART NUMBER: E52D8-RX0X4X-L

- SHIELD PLATING:
 - 1- TIN PLATING
 - 2- NICKEL PLATING
- GOLD PLATING:
 - 1- 3u" 2- 6u"
 - 3- 15u" 4- 30u"
 - 5- 50u"
- 0-PBT+15%GF(BK)
- 1-PBT+30%GF (BK)
- B-FR52 BK

← MM (INCH) →		DFTO BASS	DATE 7/8/97
TOLERANCES EXCEPT AS NOTED		CHKD SAMMY	DATE 2005/1/5
		MFO	DATE
		APPVLLUSHENG	DATE 2005/1/5
MM			
.0 ±0.20	±		
.00 ±0.15	±		
.000 ±0.075	±		
ANGLES ±		MATERIAL :	
THIRD ANGLE PROJECTION		QTY :	
		FINISH :	
		SCALE : 3:1	

FULL RISE ELECTRONIC CO., LTD

TITLE
RJ45 TOP ENTRY PCB MODULAR JACK(DIP TYPE)

DRAWING NO. GE523070	SIZE A3	REV 3
/PART NO. SEE NOTE		
DO NOT SCALE DRAWING	SHEET X	OF Y